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SN74ALVCHR16245
16-BIT BUS TRANSCEIVER
WITH 3-STATE OUTPUTS
SCES064G−DECEMBER 1995−REVISED OCTOBER 2004

FEATURES

- **Member of the Texas Instruments Widebus™ Family**

- **Operates From 1.65 V to 3.6 V**

- **Max t_{pd} of 4.2 ns at 3.3 V**

- **±12-mA Output Drive at 3.3 V**

- **All Outputs Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required**

- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**

- **Latch-Up Performance Exceeds 250 mA Per JESD 17**

- **ESD Protection Exceeds JESD 22**
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

DESCRIPTION/ORDERING INFORMATION

This 16-bit (dual-octal) noninverting bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCHR16245 is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can be used to disable the device so that the buses are effectively isolated.

DGG OR DL PACKAGE
(TOP VIEW)

1DIR	1	48	1$\overline{OE}$
1B1	2	47	1A1
1B2	3	46	1A2
GND	4	45	GND
1B3	5	44	1A3
1B4	6	43	1A4
V_{CC}	7	42	V_{CC}
1B5	8	41	1A5
1B6	9	40	1A6
GND	10	39	GND
1B7	11	38	1A7
1B8	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND	15	34	GND
2B3	16	33	2A3
2B4	17	32	2A4
V_{CC}	18	31	V_{CC}
2B5	19	30	2A5
2B6	20	29	2A6
GND	21	28	GND
2B7	22	27	2A7
2B8	23	26	2A8
2DIR	24	25	2$\overline{OE}$

All outputs, which are designed to sink up to 12 mA, include equivalent 26-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.
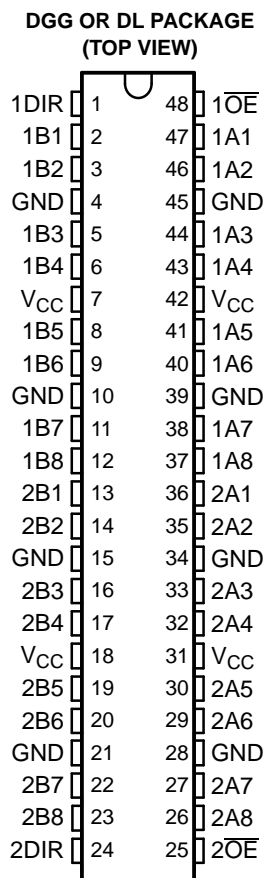
ORDERING INFORMATION

T_A	PACKAGE[1]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP - DL	Tape and reel	SN74ALVCHR16245LR	ALVCHR16245
	TSSOP - DGG	Tape and reel	SN74ALVCHR16245GR	ALVCHR16245
	VFBGA - GQL	Tape and reel	SN74ALVCHR16245KR	VR245
	VFBGA - ZQL (Pb-free)		74ALVCHR16245ZQLR	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

![Warning triangle symbol] Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.
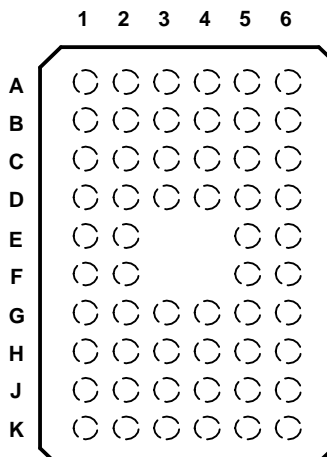
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GQL OR ZQL PACKAGE
(TOP VIEW)

TERMINAL ASSIGNMENTS[1]

	1	2	3	4	5	6
A	1DIR	NC	NC	NC	NC	1$\overline{OE}$
B	1B2	1B1	GND	GND	1A1	1A2
C	1B4	1B3	V_{CC}	V_{CC}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
H	2B5	2B6	V_{CC}	V_{CC}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2$\overline{OE}$

(1) NC - No internal connection

FUNCTION TABLE
(each 8-bit section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

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LOGIC DIAGRAM (POSITIVE LOGIC)
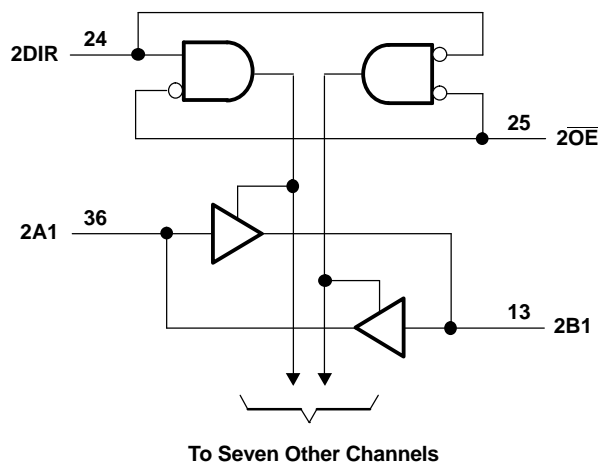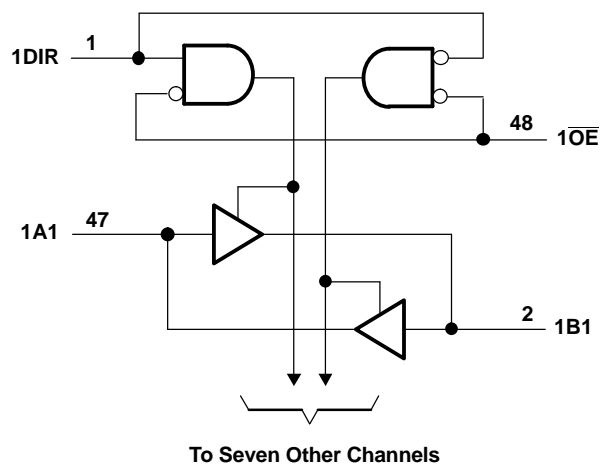
Pin numbers shown are for the DGG and DL packages.

ABSOLUTE MAXIMUM RATINGS[1]

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
V_I	Input voltage range	Except I/O ports[2]	-0.5	4.6	V
		I/O ports[2][3]	-0.5	V_{CC} + 0.5	
V_O	Output voltage range[2][3]		-0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	$V_I < 0$		-50	mA
I_{OK}	Output clamp current	$V_O < 0$		-50	mA
I_O	Continuous output current			±50	mA
	Continuous current through each V_{CC} or GND			±100	mA
θ_{JA}	Package thermal impedance[4]	DGG package		70	°C/W
		DL package		63	
		GQL/ZQL package		42	
T_{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
(3) This value is limited to 4.6 V maximum.
(4) The package thermal impedance is calculated in accordance with JESD 51-7.

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RECOMMENDED OPERATING CONDITIONS[(1)]

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	3.6	V
V_{IH}	High-level input voltage	V_{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		V
		V_{CC} = 2.3 V to 2.7 V	1.7		
		V_{CC} = 2.7 V to 3.6 V	2		
V_{IL}	Low-level input voltage	V_{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	V
		V_{CC} = 2.3 V to 2.7 V		0.7	
		V_{CC} = 2.7 V to 3.6 V		0.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65 V		-2	mA
		V_{CC} = 2.3 V		-6	
		V_{CC} = 2.7 V		-8	
		V_{CC} = 3 V		-12	
I_{OL}	Low-level output current	V_{CC} = 1.65 V		2	mA
		V_{CC} = 2.3 V		6	
		V_{CC} = 2.7 V		8	
		V_{CC} = 3 V		12	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		-40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V_{CC}	MIN	TYP[1]	MAX	UNIT
V_{OH}		I_{OH} = -100 μA	1.65 V to 3.6 V	V_{CC} - 0.2			V
		I_{OH} = -2 mA	1.65 V	1.2			
		I_{OH} = -4 mA	2.3 V	1.9			
		I_{OH} = -6 mA	2.3 V	1.7			
			3 V	2.4			
		I_{OH} = -8 mA	2.7 V	2			
		I_{OH} = -12 mA	3 V	2			
V_{OL}		I_{OL} = 100 μA	1.65 V to 3.6 V			0.2	V
		I_{OL} = 2 mA	1.65 V			0.45	
		I_{OL} = 4 mA	2.3 V			0.4	
		I_{OL} = 6 mA	2.3 V			0.55	
			3 V			0.55	
		I_{OL} = 8 mA	2.7 V			0.6	
		I_{OL} = 12 mA	3 V			0.8	
I_I		V_I = V_{CC} or GND	3.6 V			±5	μA
$I_{I(hold)}$		V_I = 0.58 V	1.65 V	25			μA
		V_I = 1.07 V		-25			
		V_I = 0.7 V	2.3 V	45			
		V_I = 1.7 V		-45			
		V_I = 0.8 V	3 V	75			
		V_I = 2 V		-75			
		V_I = 0 to 3.6 V[2]	3.6 V			±500	
I_{OZ}[3]		V_O = V_{CC} or GND	3.6 V			±10	μA
I_{CC}		V_I = V_{CC} or GND, I_O = 0	3.6 V			40	μA
ΔI_{CC}		One input at V_{CC} - 0.6 V, Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μA
C_i	Control inputs	V_I = V_{CC} or GND	3.3 V		4		pF
C_{io}	A or B ports	V_O = V_{CC} or GND	3.3 V		9		pF

(1)   All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
(2)   This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.
(3)   For I/O ports, the parameter I_{OZ} includes the input leakage current.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 1.8 V	V_{CC} = 2.5 V ± 0.2 V		V_{CC} = 2.7 V		V_{CC} = 3.3 V ± 0.3 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A or B	B or A	[1]	1	4.9		4.7	1	4.2	ns
t_{en}	$\overline{OE}$	B or A	[1]	1	6.8		6.7	1	5.6	ns
t_{dis}	$\overline{OE}$	B or A	[1]	1	6.3		5.7	1	5.5	ns

(1)   This information was not available at the time of publication.

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OPERATING CHARACTERISTICS

$T_A = 25°C$

PARAMETER			TEST CONDITIONS	$V_{CC} = 1.8$ V	$V_{CC} = 2.5$ V	$V_{CC} = 3.3$ V	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	$C_L = 50$ pF, f = 10 MHz	(1)	24	32	pF
		Outputs disabled		(1)	4	5	

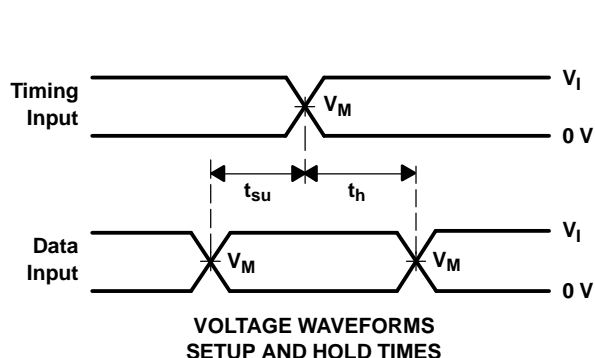(1)   This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION
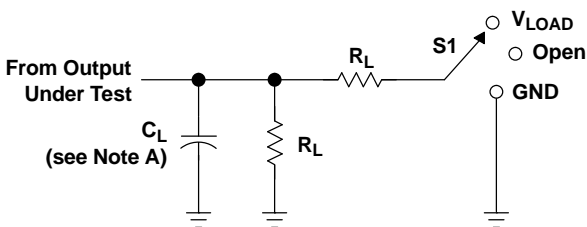
LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_Δ
	V_I	t_r/t_f					
1.8 V	V_{CC}	$\leq$2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 kΩ	0.15 V
2.5 V ± 0.2 V	V_{CC}	$\leq$2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq$2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V ± 0.3 V	2.7 V	$\leq$2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATION

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
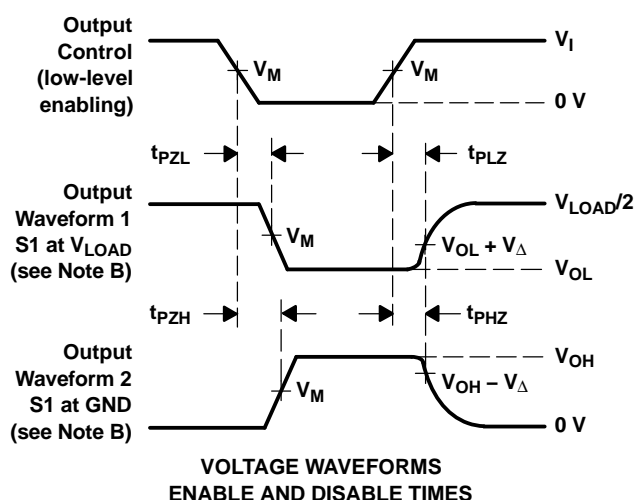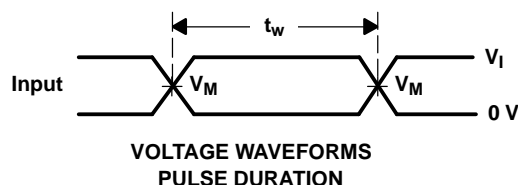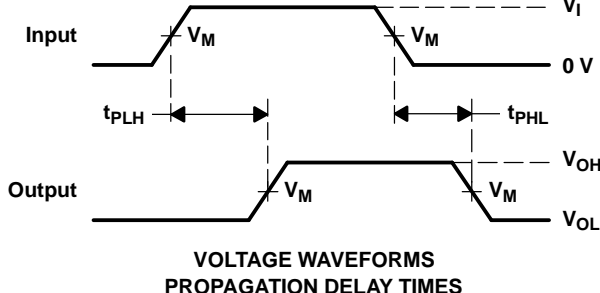
NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$ 10 MHz, Z_O = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PZL} and t_{PZH} are the same as t_{en}.
G. t_{PLH} and t_{PHL} are the same as t_{pd}.
H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
74ALVCHR16245GRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCHR16245LRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCHR16245ZQLR	ACTIVE	VFBGA	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SN74ALVCHR16245GR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCHR16245KR	ACTIVE	VFBGA	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74ALVCHR16245LR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

[1] The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)
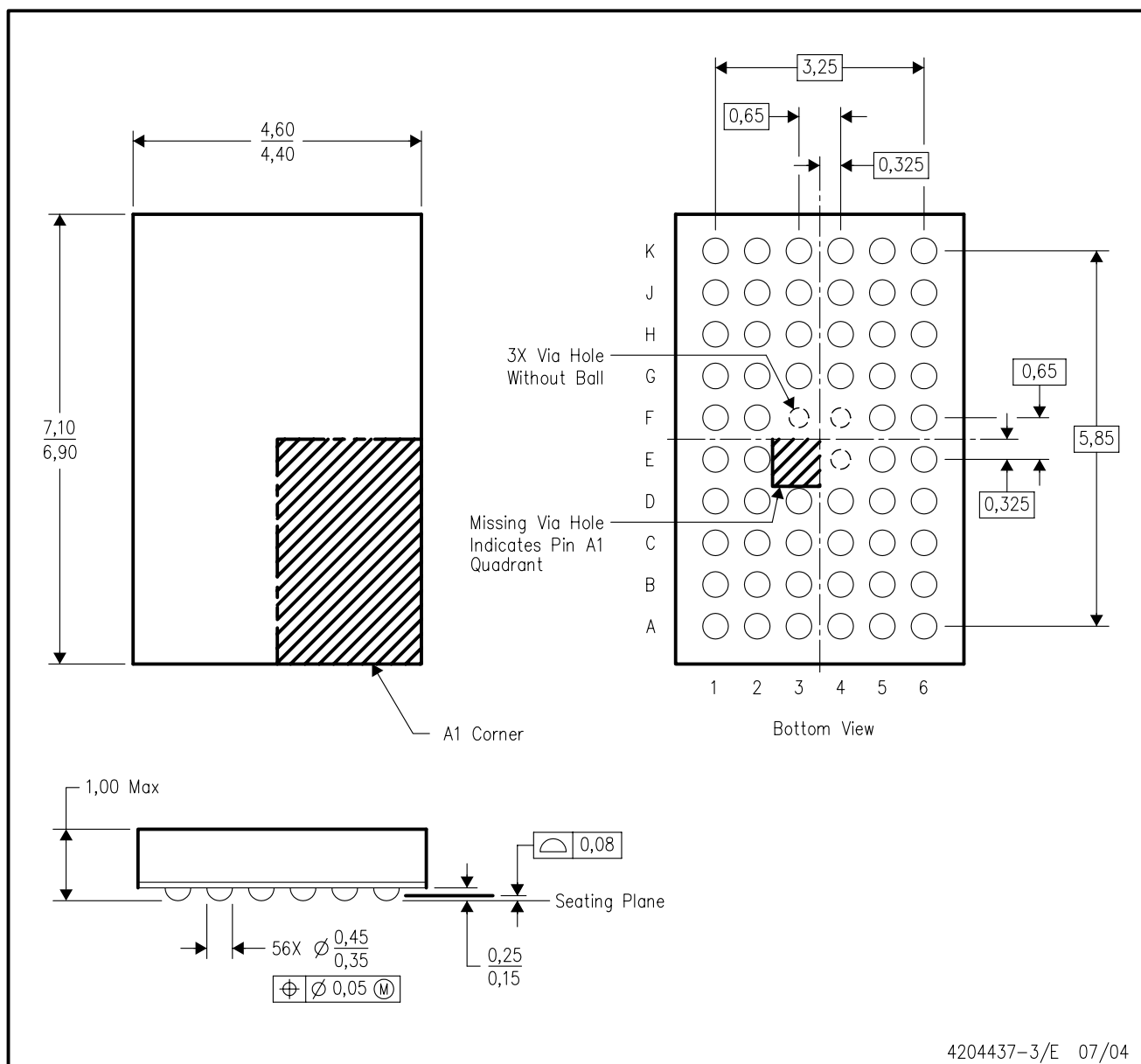
[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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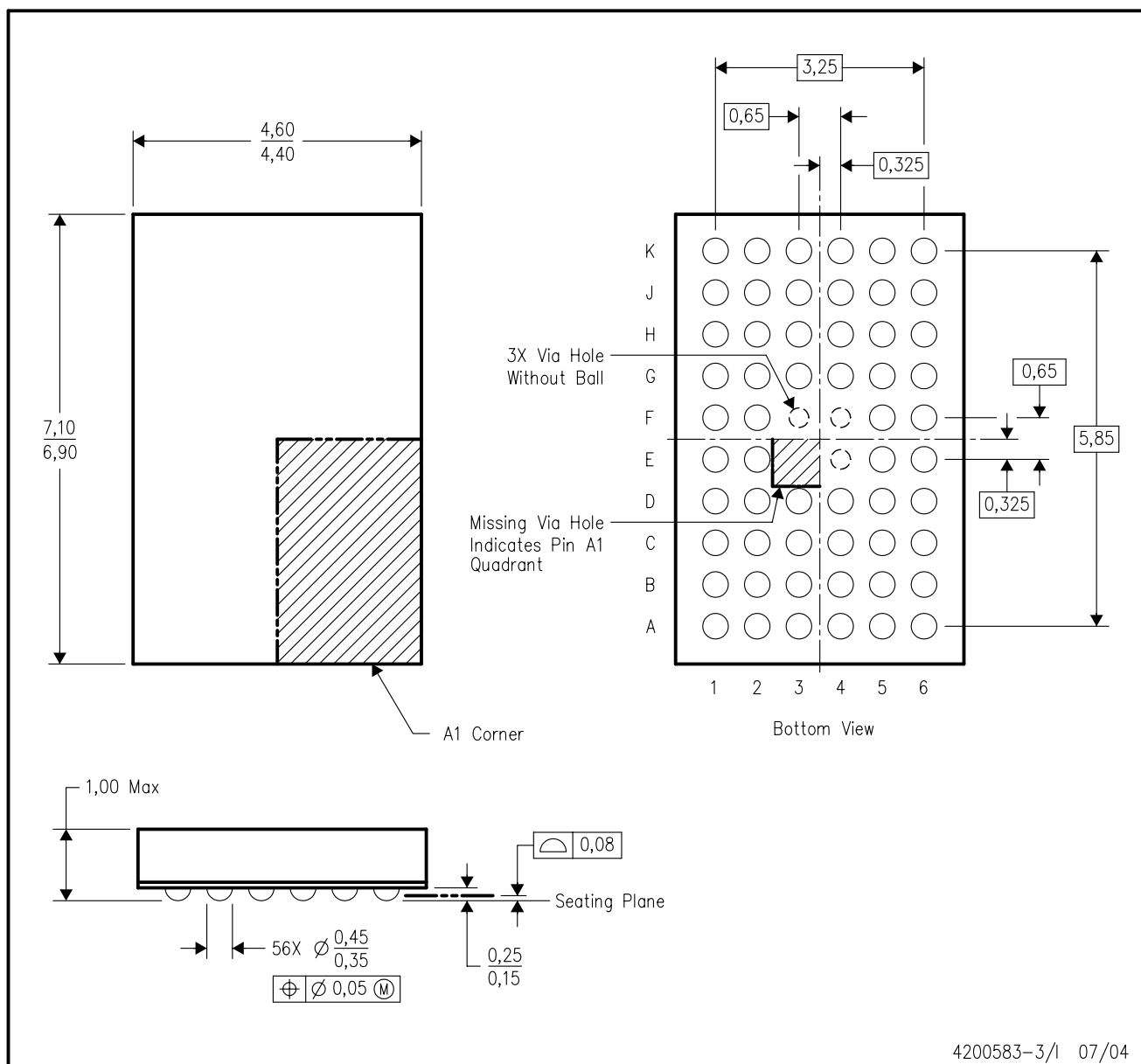
ZQL (R−PBGA−N56)　　　　　　　　　PLASTIC BALL GRID ARRAY

4,60 / 4,40

7,10 / 6,90

3,25

0,65

0,325

K
J
H
G
F
E
D
C
B
A

1　2　3　4　5　6

Bottom View

3X Via Hole Without Ball

Missing Via Hole Indicates Pin A1 Quadrant

A1 Corner

0,65

5,85

0,325

1,00 Max

0,08

Seating Plane

56X Ø 0,45 / 0,35

⊕ Ø 0,05 Ⓜ

0,25 / 0,15

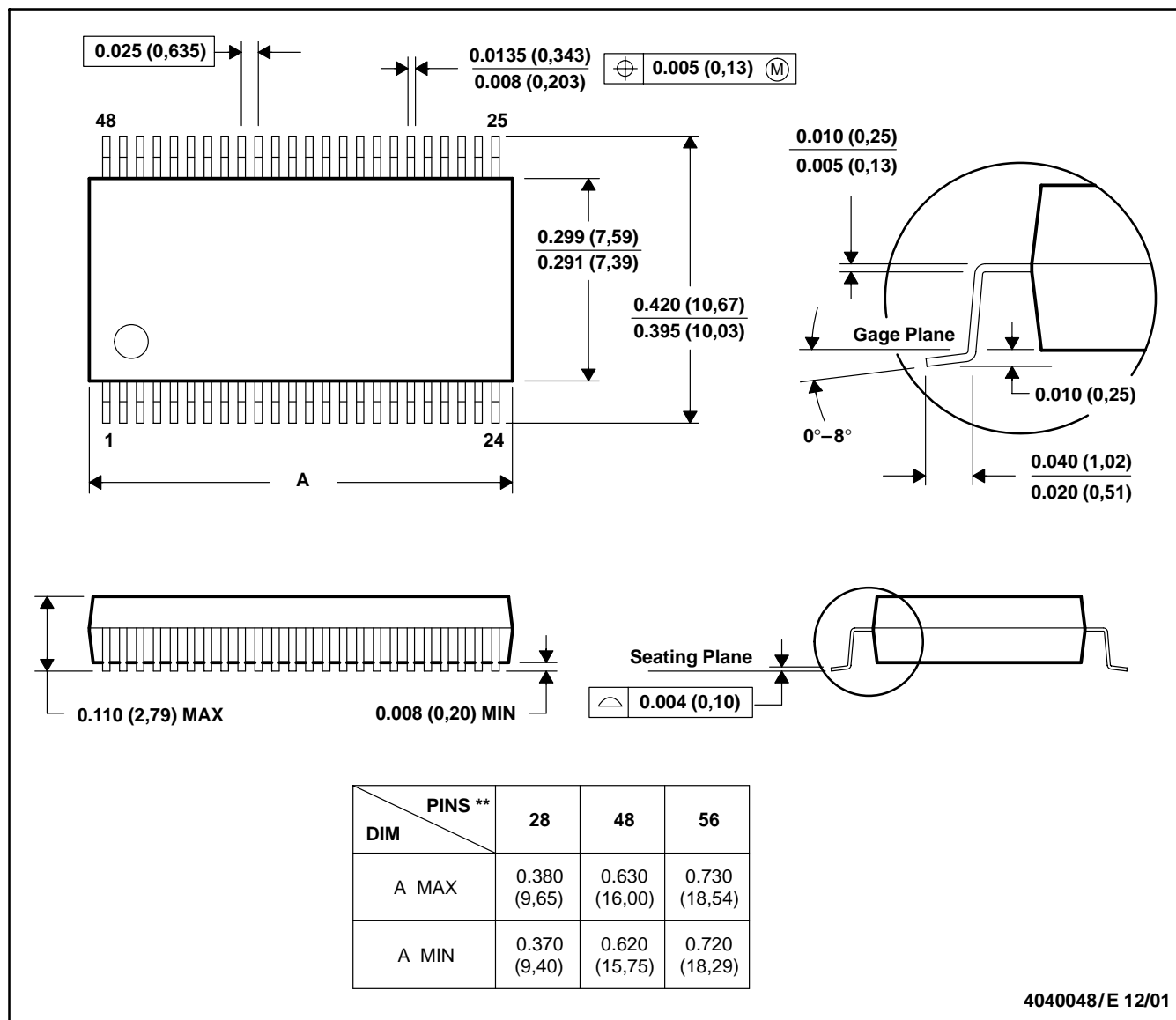4204437−3/E 07/04

NOTES:　A.　All linear dimensions are in millimeters.
　　　　　B.　This drawing is subject to change without notice.
　　　　　C.　Falls within JEDEC MO−225 variation BA.
　　　　　D.　This package is lead−free. Refer to the 56 GQL package (drawing 4200583) for tin−lead (SnPb).

GQL (R−PBGA−N56)   PLASTIC BALL GRID ARRAY

3,25

4,60
4,40

0,65

0,325

K
J
H

3X Via Hole
Without Ball

G
F

0,65

5,85

E
D

Missing Via Hole
Indicates Pin A1
Quadrant

C
B

0,325

A

7,10
6,90

1   2   3   4   5   6

Bottom View

A1 Corner

1,00 Max

⌀ 0,08

Seating Plane

56X ⌀ 0,45
0,35

0,25
0,15

⊕ ⌀ 0,05 Ⓜ

4200583−3/I 07/04

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Falls within JEDEC MO−225 variation BA.
          D.   This package is tin−lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead−free.

DL (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

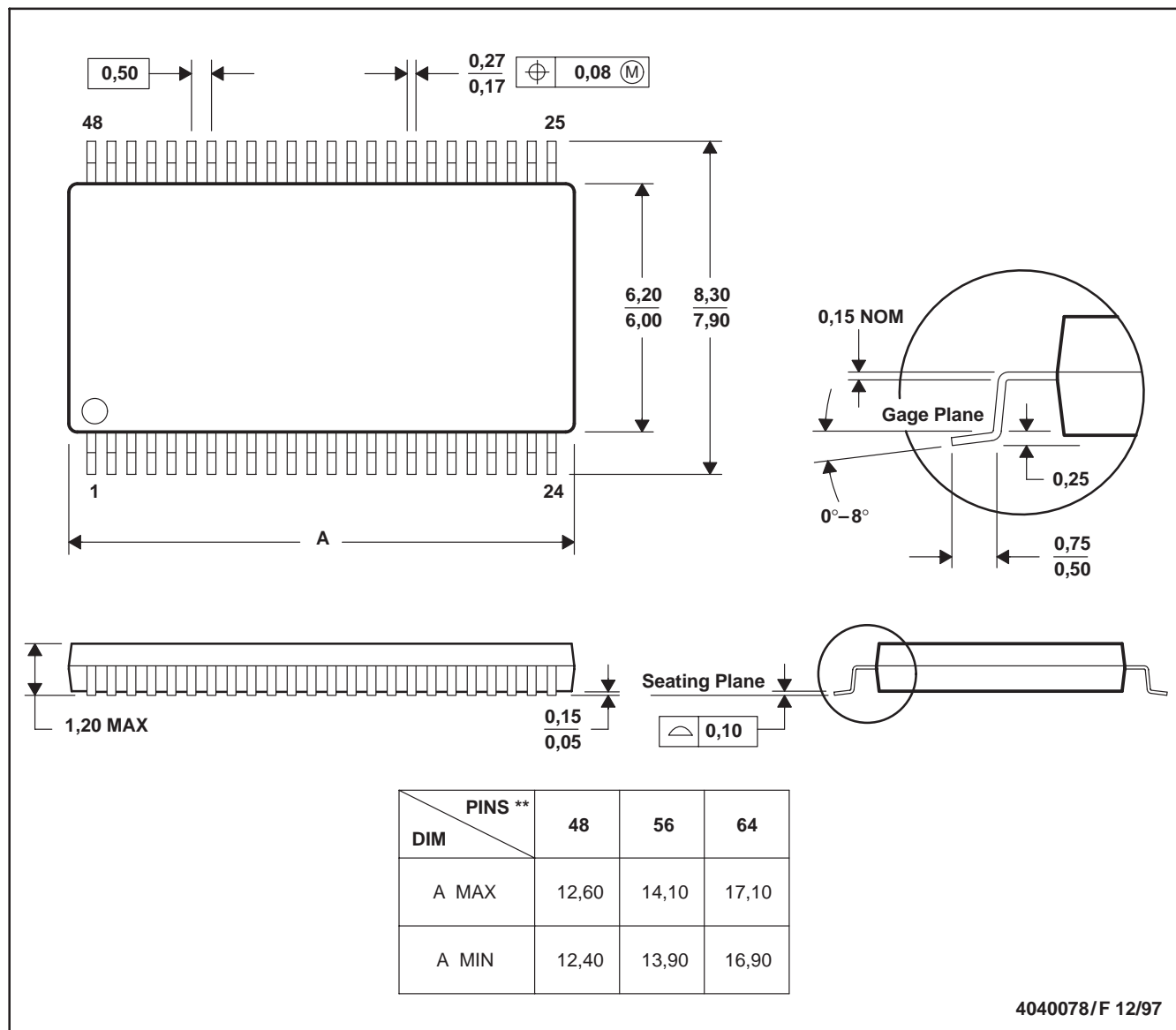| PINS ** DIM	28	48	56
A MAX	0.380 (9,65)	0.630 (16,00)	0.730 (18,54)
A MIN	0.370 (9,40)	0.620 (15,75)	0.720 (18,29)

4040048 / E 12/01

NOTES: A. All linear dimensions are in inches (millimeters).
       B. This drawing is subject to change without notice.
       C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
       D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

48 PINS SHOWN

PINS ** DIM	48	56	64
A MAX	12,60	14,10	17,10
A MIN	12,40	13,90	16,90

4040078 / F 12/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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